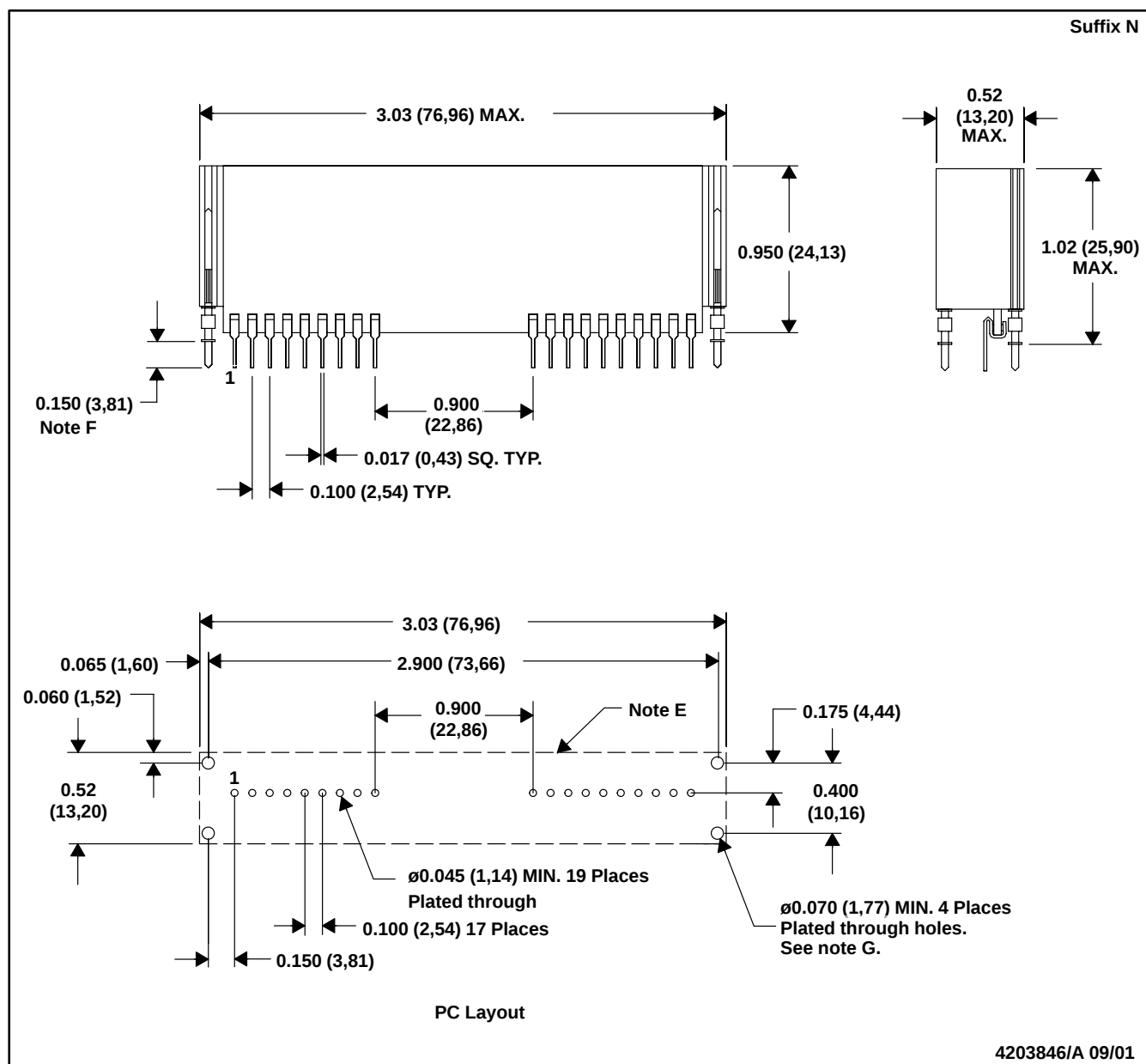


## EHG (R-MSIP-T19)

## METAL SINGLE-IN-LINE MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
  - B. This drawing is subject to change without notice.
  - C. 2 place decimals are  $\pm 0.030$  ( $\pm 0,76$ mm).
  - D. 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
  - E. Recommended mechanical keep out area.
  - F. Electrical pin length mounted on circuit board from seating plane to pin end.
  - G. The heat sink is electrically uncommitted. The recommended connection is to secondary ground plane.

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